

■ Wafer Backgrinding Protective-Film Remover

Model UH110 and UH110-8 Semiautomatic Film Removers demount film from 3" to 8" wafers after the backgrinding or etching process. The virtual 180° peeling angle ensures more efficient peeling and lower stress on the wafer, resulting in higher yields. Both systems outperform time-consuming hand removal at a fraction of the cost of fully automatic equipment. Throughput is as high as 200 wafers/hour. The standard Model UH110 can accommodate up to 6" wafers, while the Model UH110-8 handles 8" wafers and smaller. Adjustments from one size wafer to another can be made in seconds by simply changing the workstage. Push-button operation assures ease of use with all operator variables eliminated.

Features

- Short removal cycle for higher throughput
- Virtual 180* peeling angle for lower wafer stress and higher yields
- Compact, tabletop size
- Temperature-controlled (to 70°C) heated stage
- Quick peeling-tape reloading
- Easy disposal of demounted protective film
- No special operator training required
- Thin wafer stage (optional)
- Lifting-type wafer stage (optional)



Specifications model UH110

Height:	12,00"
Width:	14,00"
Depth:	28,00"

Service requirements

Vacuum:	25" Hg.
Voltage:	115/240 VAC: 50/60 Hz 3 AMPS
Air:	Operating pressure - 60PSI

Specifications model UH110-8

Height:	14,00"
Width:	16,50"
Depth:	29,00"

Service requirements

Vacuum:	25" Hg.
Voltage:	115/240 VAC: 50/60 Hz 3 AMPS
Air:	Operating pressure - 60PSI